



- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

### Product Summary

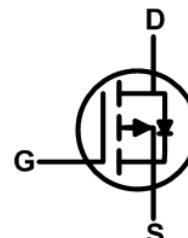
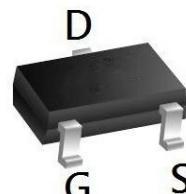
BVDSS	RDS(on)	ID
-20V	28mΩ	-5.0A

### Description

The SI2305A is the high cell density trenched P-ch MOSFETs, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications.

The SI2305A meet the RoHS and Green Product requirement with full function reliability approved.

### SOT 23 Pin Configurations



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-20	V
V <sub>GS</sub>	Gate-Source Voltage	±12	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>	-5.0	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>	-3.0	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-16	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>3</sup>	1.31	W
P <sub>D</sub> @T <sub>A</sub> =70°C	Total Power Dissipation <sup>3</sup>	0.84	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	125	°C/W
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup> (t ≤ 10s)	---	---	°C/W

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

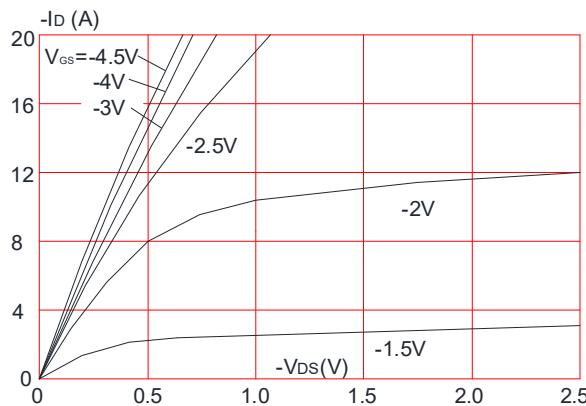
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D = -250\mu\text{A}$	-20	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = -20\text{V}$ , $V_{GS}=0\text{V}$ ,	-	-	-1	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS} = \pm 12\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D = -250\mu\text{A}$	-0.4	-0.7	-1.0	V
$R_{DS(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{GS} = -4.5\text{V}$ , $I_D = -4.1\text{A}$	-	28	35	$\text{m}\Omega$
		$V_{GS} = -2.5\text{V}$ , $I_D = -3\text{A}$	-	38	53	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = -10\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	830	-	pF
$C_{oss}$	Output Capacitance		-	132	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	85	-	pF
$Q_g$	Total Gate Charge	$V_{DS} = -10\text{V}$ , $I_D = -2\text{A}$ , $V_{GS} = -4.5\text{V}$	-	8.8	-	nC
$Q_{gs}$	Gate-Source Charge		-	1.4	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	1.9	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -10\text{V}$ , $I_D = -3.3\text{A}$ , $R_G = 1\Omega$ , $V_{GEN} = -4.5\text{V}$	-	10	-	ns
$t_r$	Turn-on Rise Time		-	32	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	50	-	ns
$t_f$	Turn-off Fall Time		-	51	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	-5.0	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-16	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_S = -4.1\text{A}$	-	-	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

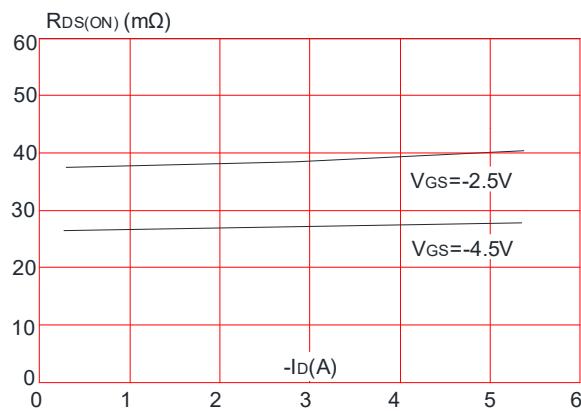
2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 2\%$

## Typical Performance Characteristics

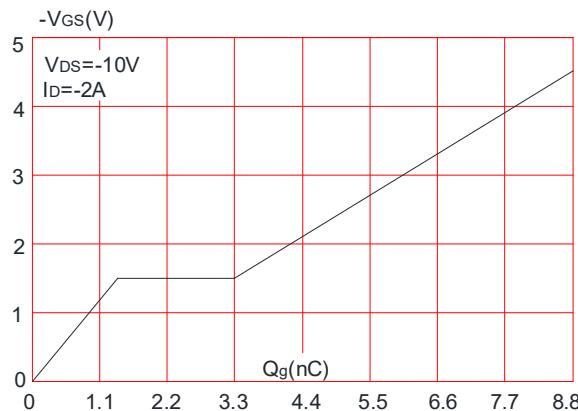
**Figure 1:** Output Characteristics



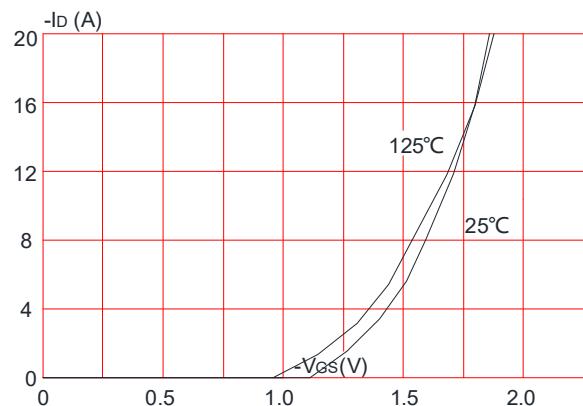
**Figure 3:** On-resistance vs. Drain Current



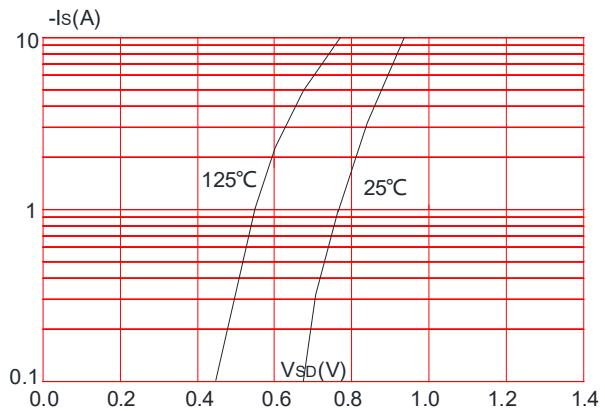
**Figure 5:** Gate Charge Characteristics



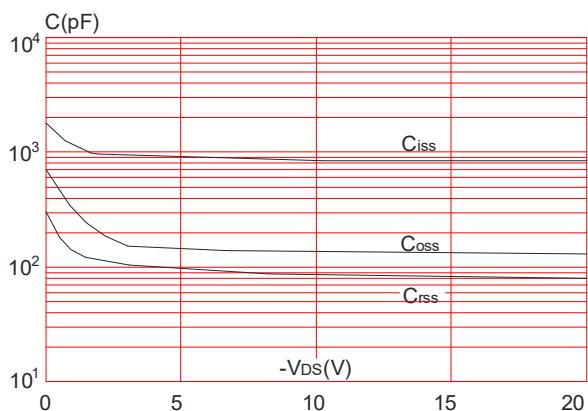
**Figure 2:** Typical Transfer Characteristics



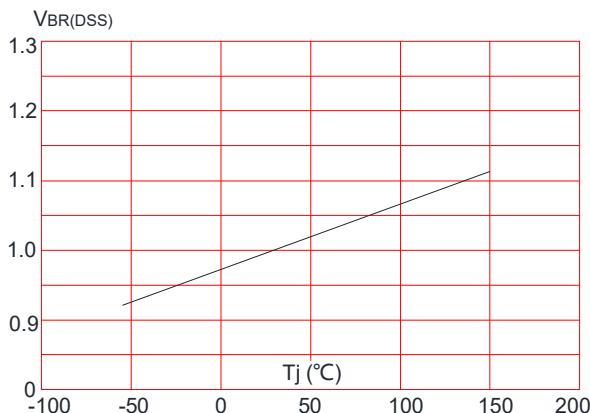
**Figure 4:** Body Diode Characteristics



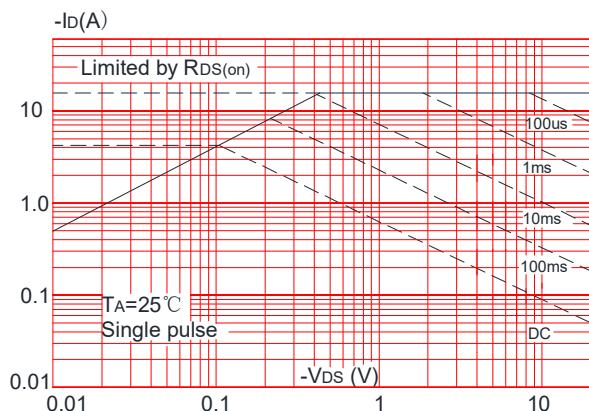
**Figure 6:** Capacitance Characteristics



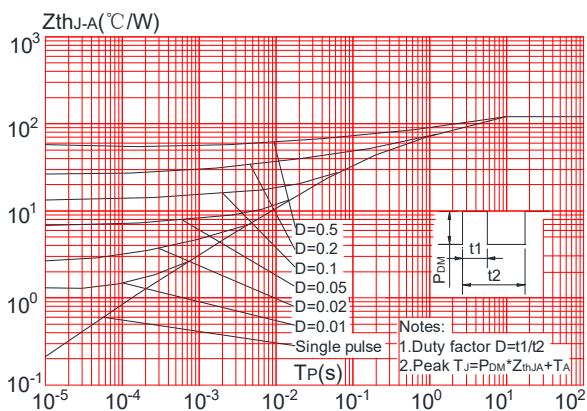
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



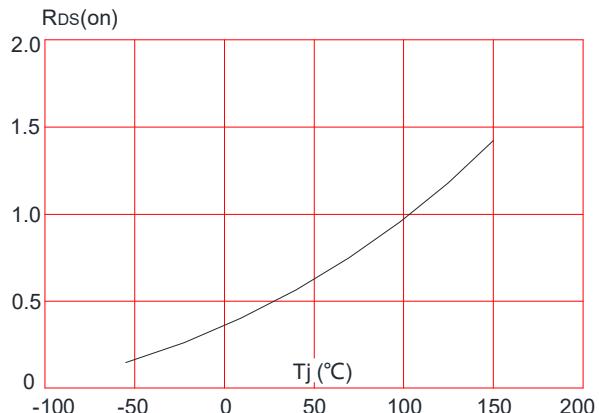
**Figure 9:** Maximum Safe Operating Area



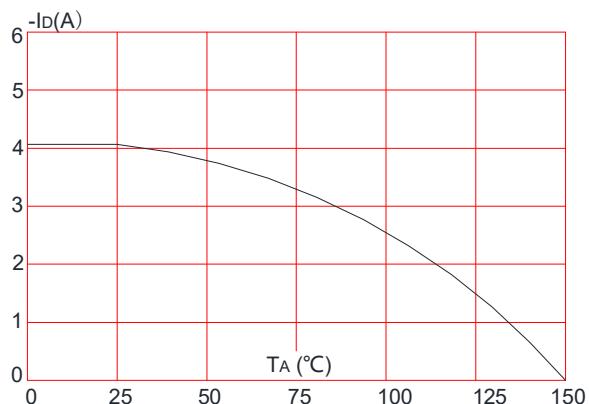
**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

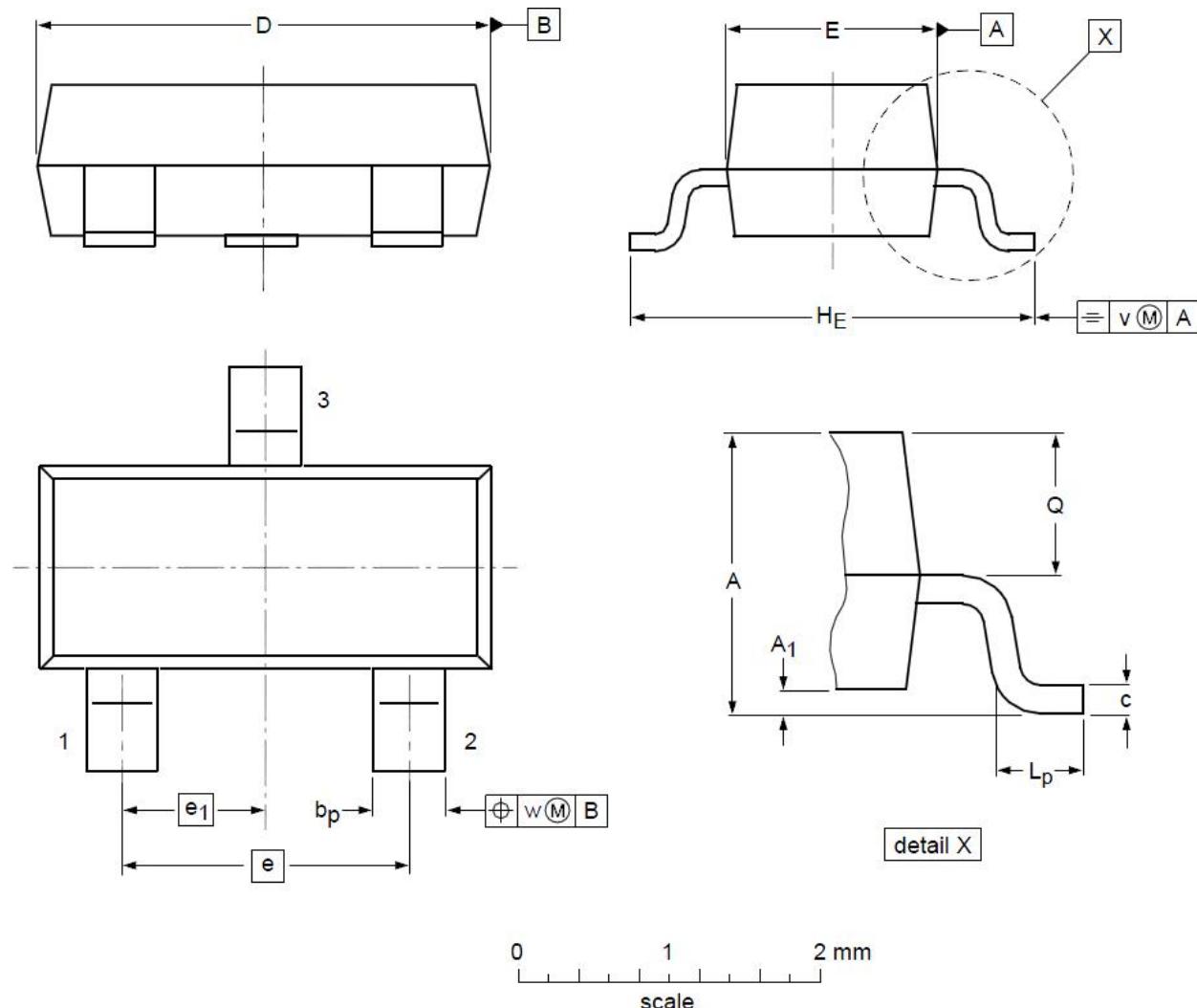


**Figure 8:** Normalized on Resistance vs. Junction Temperature



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



**Package Mechanical Data-SOT-23**

**DIMENSIONS ( unit : mm )**

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
<b>A</b>	0.90	1.01	1.15	<b>A<sub>1</sub></b>	0.01	0.05	0.10
<b>b<sub>p</sub></b>	0.30	0.42	0.50	<b>c</b>	0.08	0.13	0.15
<b>D</b>	2.80	2.92	3.00	<b>E</b>	1.20	1.33	1.40
<b>e</b>	--	1.90	--	<b>e<sub>1</sub></b>	--	0.95	--
<b>H<sub>E</sub></b>	2.25	2.40	2.55	<b>L<sub>p</sub></b>	0.30	0.42	0.50
<b>Q</b>	0.45	0.49	0.55	<b>v</b>	--	0.20	--
<b>w</b>	--	0.10	--				